



Product code : 50105L

## ISOLEMFI 50105L MONO

### DESCRIPTION

Very fast moisture curing one-part polyurethane adhesive.

### AREAS OF APPLICATION

ISOLEMFI 50105L MONO may be used for bonding hard insulating foams like extruded or expanded polystyrene and phenolic foam or of panels from mineral wool on plaster boards (with or without vapour shield), fibre cement, steel sheets for production of partition walls and thermal insulation elements.

### TECHNICAL DATA

Colour	Red
Viscosity at 20 °C	Brookfield RVT spindle 4 / 10 rpm : 4,000 ± 1,000 mPa.s
Density at 20 °C	1.125 ± 0.010
Conventional solids content (EN 827)	> 99 %
Open time at 20 °C	2 min*
Pressing time at 20 °C	13 to 18 min*
Final setting time at 20 °C	2 h*
Calorific power	31 MJ/kg
Temperature resistance of the assemblies	-40 to +100 °C
Cleaner	EMFINET 683 before setting

\* in case of water mist spraying upon the layer of the adhesive

### ADVICE

See also material safety data sheet



### INSTRUCTIONS FOR USE

#### Substrates preparation :

The substrates to be assembled must be flat, dry, dust free and not have any traces of grease or other contaminants that could adversely affect the bonding performance.

If the substrates need to be cleaned, EMFINET 683 or methylethylketone (MEK) may be used. Solvents must comply with local regulations. Check the compatibility of the solvent used with the substrates. If necessary, rub down metal surfaces beforehand.

When using solvents, extinguish all sources of ignition and carefully follow the safety and handling instructions given by the manufacturer or supplier.

#### Application :

The adhesive is applied on one of the substrates to be bonded with a spray gun or a roller, or in strips.

One of the materials to be bonded must be porous or contain moisture.

If both substrates are non porous, it is imperative to spray a light water mist (10 to 15 g/m<sup>2</sup>) onto the adhesive film.

The setting time depends on hygrometry and temperature. So it is necessary :

- in case of working under 20 °C : to be sure that the pressing time is long enough
  - in case of working over 20 °C : to be sure that open time and closed assembly time are not excessive
- Otherwise, defective bonding could happen.

If necessary, refer to our technical service.

Assembling has to be followed by a uniform and maximum pressure applied across the entire surface without irreversible deformation of substrates.

Cleaning :

Tools can be cleaned with EMFINET 683 or MEK before the adhesive has completely cured. After curing, abrasion is necessary.

## CONSUMPTION

100 to 150 g/m<sup>2</sup> according to the materials to be bonded

## STORAGE AND SHELF LIFE

3 months in closed original packaging stored in dry premises between 10 and 25 °C

## PACKAGING

1 kg bottles ; 60 and 220 kg metal drums ; 1,000 kg containers

## SAFETY

Harmful. Read material safety data sheet before use.

The technical data contained herein is based on our present knowledge and experience and we cannot be held liable for any errors, inaccuracies, omissions or editorial failings that result from technological changes or research between the date of issue of this document and the date the product is acquired.

Before using the product, the user should carry out any necessary tests in order to ensure that the product is suitable for the intended application. Moreover, all users should contact the seller or the manufacturer of the product for additional technical information concerning its use if they think that the information in their possession needs to be clarified in any way, whether for normal use or a specific application of our product.

Our guarantee applies within the context of the statutory regulations and provisions in force, current professional standards and in accordance with the stipulations set out in our general sales conditions.

The information detailed in the present technical data sheet is given by way of indication and is not exhaustive. The same applies to any information provided verbally by telephone to any prospective or existing customer.